

TinyLogic UHS 2-Input Non-Inverting Multiplexer

NC7SZ157

Description

The NC7SZ157 is a single, high performance, 2-to-1 CMOS non-inverting multiplexer from onsemi's Ultra-High Speed series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating range.

Features

- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Ultra High-Speed
- Power Down High-Impedance Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra-Small MicroPak[™] Packages
- Space-Saving SC-88 Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

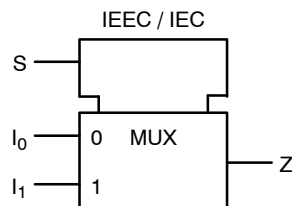
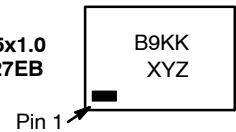


Figure 1. Logic Symbol

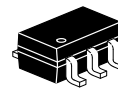
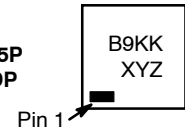
MARKING DIAGRAMS



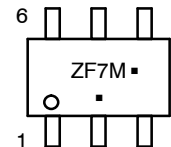
SIP6 1.45x1.0
CASE 127EB



UDFN6
1.0X1.0, 0.35P
CASE 517DP



SC-88
CASE 419B-02



B9, ZF7 = Specific Device Code
 KK = 2-Digit Lot Run Traceability Code
 XY = 2-Digit Date Code Format
 Z = Assembly Plant Code
 M = Date Code*
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

Pin Configurations

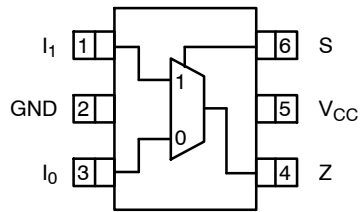


Figure 2. SC-88 (Top View)

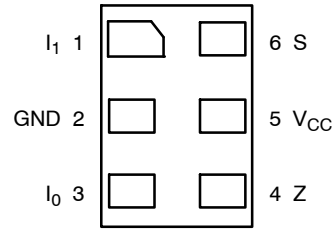
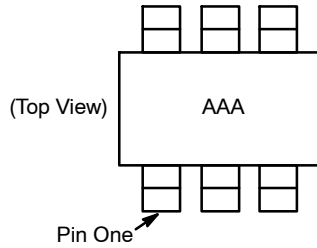


Figure 3. MicroPak (Top Through View)



NOTES:

1. AAA represents product code top mark (see *Ordering Information*).
2. Orientation of top mark determines pin one location.
3. Reading the top mark left to right, pin one is the lower left pin.

Figure 4. Pin 1 Orientation

PIN DEFINITIONS

Pin # SC-88	Pin # MicroPak	Name	Description
1	1	I ₁	Data Input
2	2	GND	Ground
3	3	I ₀	Data Input
4	4	Z	Output
5	5	V _{CC}	Supply Voltage
6	6	S	Control Input

FUNCTION TABLE

Inputs			Output
S	I ₁	I ₀	$Z = (I_0) \cdot (\bar{S}) + (I_1) \cdot (S)$
L	X	L	L
L	X	H	H
H	L	X	L
H	H	X	H

H = HIGH Logic Level
L = LOW Logic Level
X = Don't Care

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Supply Voltage		–0.5	6.5	V
V _{IN}	DC Input Voltage		–0.5	6.5	V
V _{OUT}	DC Output Voltage		–0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	–	–50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	–	–50	mA
I _{OUT}	DC Output Current		–	±50	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		–	±50	mA
T _{STG}	Storage Temperature Range		–65	+150	°C
T _J	Junction Temperature Under Bias		–	+150	°C
T _L	Junction Lead Temperature (Soldering, 10 Seconds)		–	+260	°C
P _D	Power Dissipation in Still Air	SC–88	–	332	mW
		MicroPak–6	–	812	
		MicroPak2™–6	–	812	
ESD	Human Body Model, JEDEC: JESD22–A114		–	4000	V
	Charge Device Model, JEDEC: JESD22–C101		–	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.50	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		–40	+85	°C
t _r , t _f	Input Rise and Fall Times	V _{CC} at 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} at 3.3 V ±0.3 V	0	10	
		V _{CC} at 5.0 V ±0.5 V	0	5	
θ _{JA}	Thermal Resistance	SC–88	–	377	°C/W
		MicroPak–6	–	154	°C/W
		MicroPak2–6	–	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

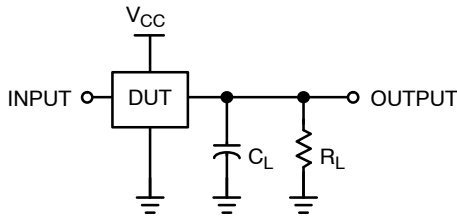
DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	HIGH Level Input Voltage	1.65 to 1.95		0.65 V _{CC}	–	–	0.65 V _{CC}	–	V
		2.30 to 5.50		0.70 V _{CC}	–	–	0.70 V _{CC}	–	
V _{IL}	LOW Level Input Voltage	1.65 to 1.95		–	–	0.35 V _{CC}	–	0.35 V _{CC}	V
		2.30 to 5.50		–	–	0.30 V _{CC}	–	0.30 V _{CC}	
V _{OH}	HIGH Level Output Voltage	1.65	V _{IN} = V _{IH} or V _{IL}	I _{OH} = –100 μA	1.55	1.65	–	1.55	V
		2.30			2.20	2.30	–	2.20	
		3.00			2.90	3.00	–	2.90	
		4.50			4.40	4.50	–	4.40	
		1.65			1.29	1.52	–	1.29	
		2.30		I _{OH} = –8 mA	1.90	2.15	–	1.90	
		3.00		I _{OH} = –16 mA	2.40	2.80	–	2.40	
		3.00		I _{OH} = –24 mA	2.30	3.68	–	2.30	
		4.50		I _{OH} = –32 mA	3.90	4.20	–	3.80	
V _{OL}	LOW Level Output Voltage	1.65	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 100 μA	–	0	0.10	–	V
		2.30			–	0	0.10	–	
		3.00			–	0	0.10	–	
		4.50			–	0	0.10	–	
		1.65		I _{OL} = 4 mA	–	0.08	0.24	–	
		2.30		I _{OL} = 8 mA	–	0.10	0.30	–	
		3.00		I _{OL} = 16 mA	–	0.15	0.40	–	
		3.00		I _{OL} = 24 mA	–	0.22	0.55	–	
		4.50		I _{OL} = 32 mA	–	0.22	0.55	–	
I _{IN}	Input Leakage Current	1.65 to 5.5		V _{IN} = 5.5 V, GND	–	–	±0.1	–	μA
I _{OFF}	Power Off Leakage Current	0		V _{IN} or V _{OUT} = 5.5 V	–	–	1.0	–	10 μA
I _{CC}	Quiescent Supply Current	1.65 to 5.50		V _{IN} = 5.5 V, GND	–	–	1.0	–	10 μA

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = +25°C			T _A = -40 to +85°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay S to Z (Figure 5, 6)	1.80 ±0.15	C _L = 15 pF, R _L = 1 MΩ,	–	6.0	11.5	–	12.0	ns
		2.50 ±0.20		–	3.5	6.1	–	6.5	
		3.30 ±0.30		–	2.6	4.1	–	4.5	
		5.00 ±0.50		–	1.9	3.2	–	3.5	
	Propagation Delay I _n to Z (Figure 5, 6)	1.80 ±0.15	C _L = 15 pF, R _L = 1MΩ,	–	5.9	10.0	–	10.5	
		5.00 ±0.50		–	3.5	5.8	–	6.1	
		3.30 ±0.30		–	2.6	3.9	–	4.2	
		5.00 ±0.50		–	1.9	3.1	–	3.3	
	Propagation Delay S to Z (Figure 5, 6)	3.30 ±0.30	C _L = 50 pF, R _L = 500 Ω,	–	3.2	4.8	–	5.2	
		5.00 ±0.50		–	2.4	3.8	–	4.1	
	Propagation Delay I _n to Z (Figure 5, 6)	3.30 ±0.30	C _L = 50 pF, R _L = 500 Ω,	–	3.2	4.6	–	5.0	
		5.00 ±0.50		–	2.4	3.7	–	4.0	
C _{IN}	Input Capacitance	0.00		–	2	–	–	–	pF
C _{PD}	Power Dissipation Capacitance (Note 4) (Figure 7)	3.30		–	14	–	–	–	pF
		5.00		–	17	–	–	–	

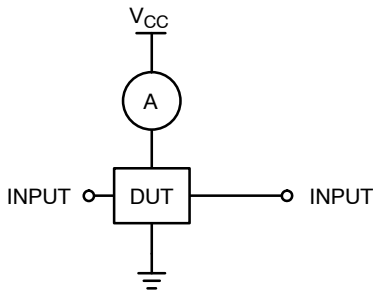
4. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic}).



NOTE:

5. C_L includes load and stray capacitance; inputs PRR = 1.0 MHz, t_W = 500 ns.

Figure 5. AC Test Circuit



NOTE:

6. Input = AC Waveform; PRR = Variable; Duty Cycle = 50%.

Figure 7. I_{CCD} Test Circuit

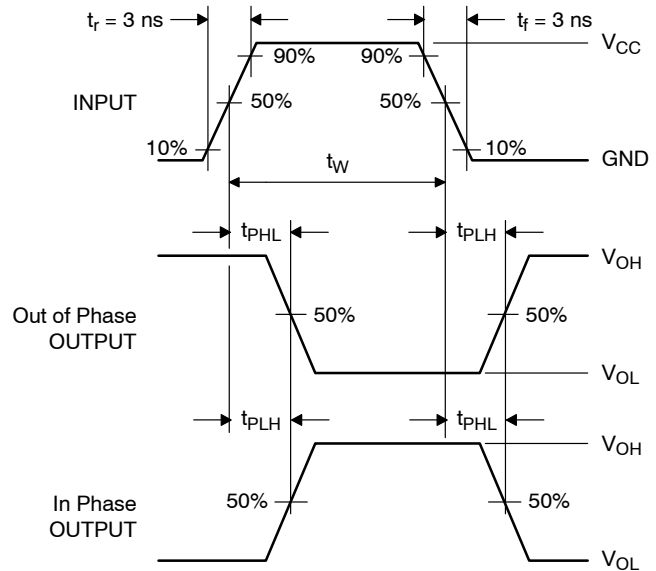


Figure 6. AC Waveforms

NC7SZ157

DEVICE ORDERING INFORMATION

Device	Top Mark	Packages	Shipping†
NC7SZ157P6X	ZF7	6-Lead SC70, EIAJ SC-88, 1.25 mm Wide	3000 / Tape & Reel
NC7SZ157P6X-L22347	ZF7	6-Lead SC70, EIAJ SC-88, 1.25 mm Wide	3000 / Tape & Reel
NC7SZ157L6X	B9	6-Lead MicroPak, 1.00 mm Wide	5000 / Tape & Reel
NC7SZ157L6X-L22175	B9	6-Lead MicroPak, 1.00 mm Wide	5000 / Tape & Reel
NC7SZ157FHX	B9	6-Lead, MicroPak2, 1x1 mm Body, .35 mm Pitch	5000 / Tape & Reel
NC7SZ157FHX-L22175	B9	6-Lead, MicroPak2, 1x1 mm Body, .35 mm Pitch	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ON

DATE 31 AUG 2016



NOTES:

1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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SCALE 2:1

SC-88/SC70-6/SOT-363
CASE 419B-02
ISSUE Y

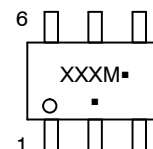
DATE 11 DEC 2012



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 4. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 5. DATUMS A AND B ARE DETERMINED AT DATUM H.
 6. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.10	---	---	0.043
A1	0.00	---	0.10	0.000	---	0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
C	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10			0.004		

GENERIC MARKING DIAGRAM*



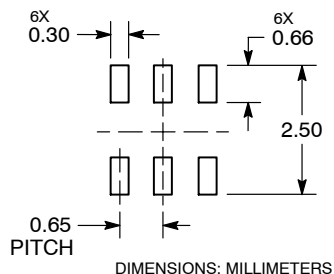
XXX = Specific Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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CASE 419B-02
ISSUE Y

DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. IOUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

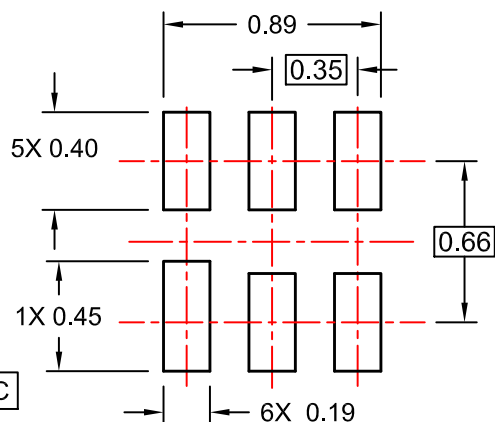
Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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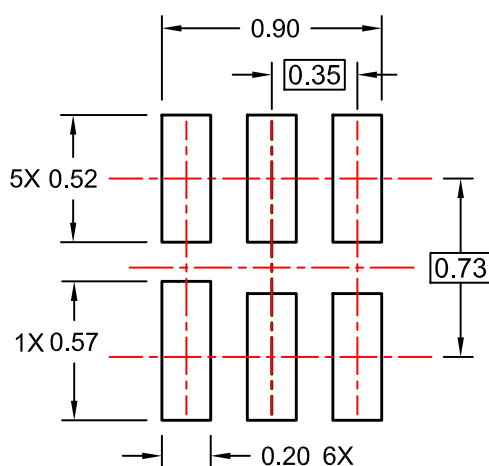
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The side view shows a rectangular part with three small rectangular features on its top surface. A feature control frame is located at the top right, containing a surface texture symbol (two parallel lines), a tolerance of 0.05, and a material condition symbol 'C'. A dimension line indicates a vertical distance of 0.50 ± 0.05 from the top surface to the top of the part. A datum feature control frame with the letter 'C' is shown on the left side of the part.



Technical drawing of a detail of a pin 1 lead. The drawing shows a cross-section of a rectangular feature with a chamfered corner. Dimensions include a width of $(0.05) 6X$, a height of 0.35 ± 0.050 , and a chamfer of $0.075X45^\circ$. A callout box contains the letters C, B, and A. The drawing is labeled "DETAIL A" and "PIN 1 LEAD SCALE: 2X".

A. COMPLIES TO JEDEC MO-252 STANDARD
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009

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